

**Serial No. 10/516,084**  
**Atty. Doc. No. 2002P07513WOUS**

**In the Specification:**

**Please replace the Abstract with the following new paragraph.**

**An apparatus for monitoring the structural integrity of a component. A monitoring structure is applied to a component that is subject to structural degradation. The monitoring structure includes an electrical conductor that becomes cracked if the component becomes structurally degraded. When the component is a ductile metal component that may be degraded by bending, the electrical conductor is formed of a brittle material that cracks when the ductile metal component is bent. When the component is a brittle ceramic heat shield wherein a crack having a critical length is of concern, the electrical conductor is located at a predetermined location wherein a critical length crack in the component will propagate into the conductor. A crack in the electrical conductor is detected with a monitoring device to indicate a degraded structural condition in the component.**